

AON7752-VB Datasheet

N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a	Q _g (Typ.)		
30	0.0045 at V _{GS} = 10 V	40	26.5 nC		
30	0.0060 at V _{GS} = 4.5 V	33.3	20.5 110		

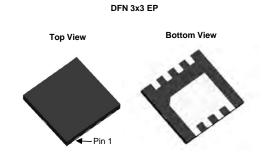
FEATURES

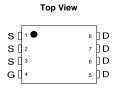
- · Halogen-free
- Trench Power MOSFET
- 100 % R_g and UIS Tested

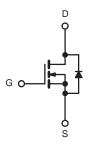


APPLICATIONS

- DC/DC Conversion
 - Low-Side Switch
- Notebook PC
- Gaming







N-Channel MOSFET

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	30	V	
Gate-Source Voltage		V _{GS}	± 20	v	
	T _C = 25 °C		40		
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 70 °C	I _D	32.6		
Continuous Brain Gunent (1) = 100 G)	T _A = 25 °C	d 'D	31.5 ^{b, c}		
	T _A = 70 °C		27.1 ^{b, c}	Α	
Pulsed Drain Current		I _{DM}	70		
Cantinuary Course Dunin Diada Current	T _C = 25 °C	1-	5.4		
Continuous Source-Drain Diode Current	T _A = 25 °C	ls ===	2.7 ^{b, c}		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	40		
Avalanche Energy	L=0.11IIII	E _{AS}	80	mJ	
	T _C = 25 °C		6.0		
Maximum Power Dissipation	T _C = 70 °C	P _D	3.3	W	
Maximum Fower Dissipation	T _A = 25 °C		3.0 ^{b, c}	VV	
	T _A = 70 °C		1.9 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stq}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R_{thJA}	33	42	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	16	21	C/ V V	

Notes:

- a. Based on T_C = 25 °C. b. Surface Mounted on 1" x 1" FR4 board.
- d. Maximum under Steady State conditions is 85 °C/W.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	$\Delta V_{DS}/T_{J}$ $I_{D} = 250 \text{ µA}$		27		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			- 5.6		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	1.5		3.0	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zara Cata Valtaria Brain Comment	1	V _{DS} = 30 V, V _{GS} = 0 V			1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C			10	μΑ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α
	В	V _{GS} = 10 V, I _D = 15 A		0.0045		Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$		0.0060		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 15 A		75		S
Dynamic ^b				<u> </u>	L	
Input Capacitance	C _{iss}			2545		pF
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		450		
Reverse Transfer Capacitance	C _{rss}	1		140		
Total Cata Chargo		$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 10 \text{ A}$		62		
Total Gate Charge	Q _g			26.5		200
Gate-Source Charge	Q_{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$		8.5		nC
Gate-Drain Charge	Q_{gd}			7.3		
Gate Resistance	R_g	f = 1 MHz	0.2	1.1	2.2	Ω
Turn-On Delay Time	t _{d(on)}			35	60	
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_{L} = 1.5 \Omega$		16	30	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		48	85	
Fall Time	t _f			16	30	nc
Turn-On Delay Time	t _{d(on)}			18	35	ns -
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_{L} = 1.5 \Omega$		8	16	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		41	75	
Fall Time	t _f			8	18	
Drain-Source Body Diode Characteristi	cs					
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			5.4	Λ
Pulse Diode Forward Current ^a	I _{SM}				70	A
Body Diode Voltage	V _{SD}	I _S = 3 A		0.72	1.1	V
Body Diode Reverse Recovery Time	t _{rr}			33	65	ns
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 10 A, dl/dt = 100 A/μs, T _J = 25 °C		27	54	nC
Reverse Recovery Fall Time	t _a	$\frac{1}{1}$ $\frac{1}$		17		
Reverse Recovery Rise Time	t _b			16		ns

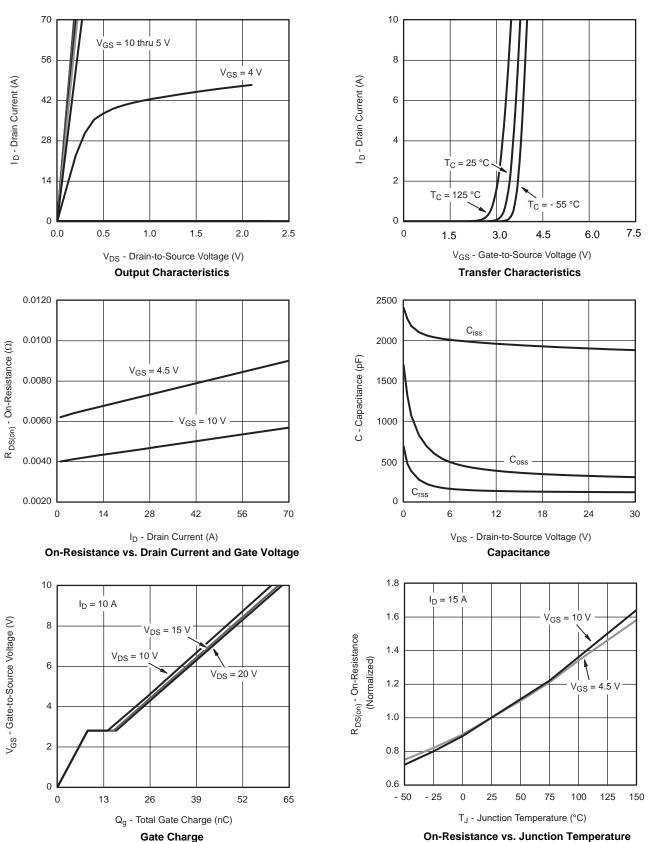
Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 % b. Guaranteed by design, not subject to production testing.

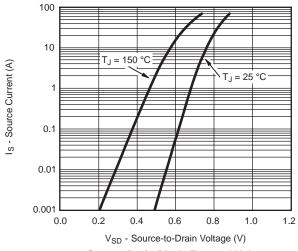


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

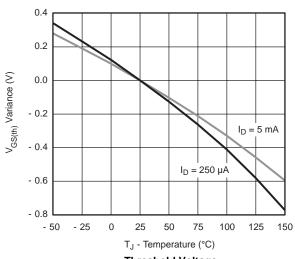


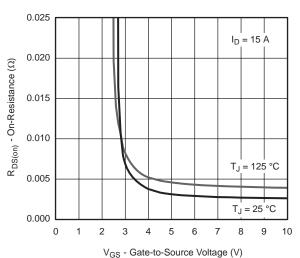


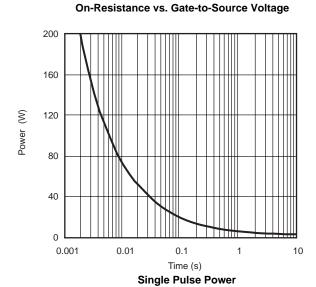
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



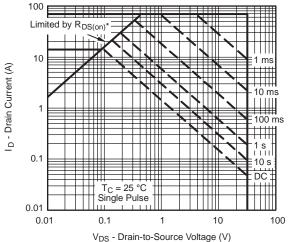
Source-Drain Diode Forward Voltage







Threshold Voltage

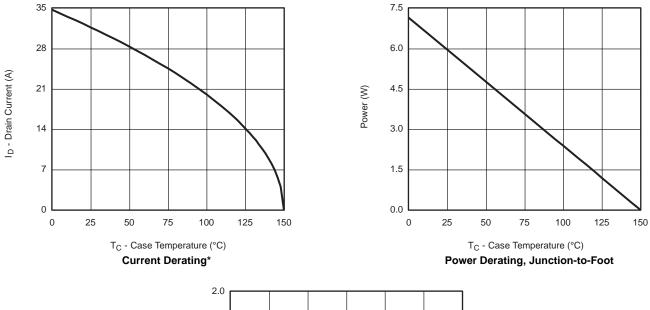


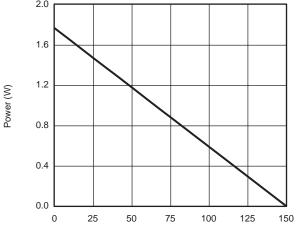
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





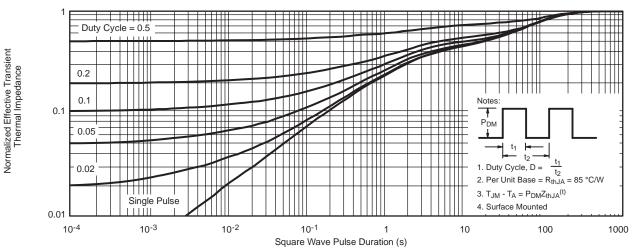
T_A - Ambient Temperature (°C)

Power, Junction-to-Ambient

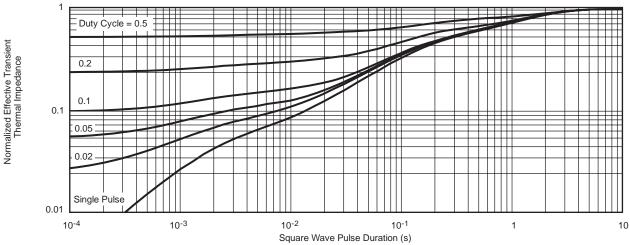
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS 25 C, unless otherwise noted

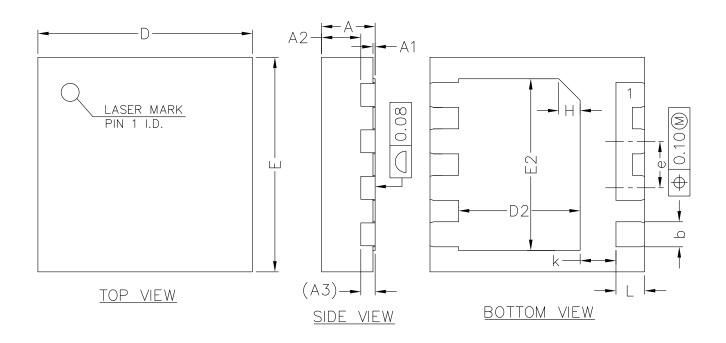


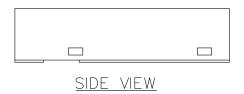
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot







COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX	
А	0.70	0.75	0.80	
A1	0.00	0.02	0.05	
A2	0.50	0.55	0.60	
А3	0.20REF			
b	0.30	0.35	0.40	
D	2.90	3.00	3.10	
Е	2.90	3.00	3.10	
D2	1.60	1.70	1.80	
E2	2.30	2.40	2.50	
е	0.55	0.65	0.75	
K	0.40	0.50	0.60	
L	0.35	0.40	0.45	



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